

WHAT IS CLAIMED IS:

Sub  
A1  
1. A cleaning method of an electronic component wherein an object to be cleaned is cleaned using a sponge member while supplying, to said object to be cleaned, cleaning water having the resistivity value of  $10M\Omega$  or less.

2. A cleaning method of an electronic component according to claim 1, wherein the resistivity value of said cleaning water is adjusted to  $5M\Omega$  or less by including carbon dioxide gas in said cleaning water.

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A2  
3. A cleaning method of an electronic component according to claim 1, wherein said sponge member is separated from said object to be cleaned during cleaning, and said cleaning water is supplied also to said separated sponge member.

4. A cleaning method of an electronic component according to claim 2, wherein said sponge member is separated from said object to be cleaned during cleaning, and said cleaning water is supplied also to said separated sponge member.

5. A cleaning method of an electronic component according to claim 1, wherein said object to be cleaned is a ceramic wafer.

6. A cleaning method of an electronic component according to claim 2, wherein said object to be cleaned is a ceramic wafer.

7. A cleaning method of an electronic component according to claim 3, wherein said object to be cleaned is a ceramic wafer.

8. A cleaning method of an electronic component according to claim 4, wherein said object to be cleaned is a ceramic wafer.

9. A cleaning method of an electronic component wherein an object to be cleaned is soaked in cleaning water having the resistivity value of  $10M\Omega$  or less before cleaning.

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A3  
10. A cleaning method of an electronic component according to any one of claims 1 to 9, wherein said object to be cleaned is soaked in said cleaning water having the resistivity value of  $10M\Omega$  or less before cleaning.

11. A handling method of an electronic component wherein a substrate which is an object to be cleaned is placed on a substrate holding piece of a substrate rack, and when said substrate is cleaned and then said substrate is placed on

another substrate holding piece of another substrate rack, a dummy substrate is located on a film formed surface of said substrate.

12. A handling method of an electronic component wherein when a substrate which is an object to be cleaned is cleaned and then is preserved in a state in which said substrate is placed on a substrate holding piece of a substrate rack, said substrate rack is inclined so that a film formed surface side does not contact with said substrate holding piece of said substrate rack.

13. A cleaning method of an electronic component according to claim 11, wherein when a substrate which is an object to be cleaned is cleaned and then is preserved in a state in which said substrate is placed on a substrate holding piece of a substrate rack, said substrate rack is inclined so that a film formed surface side does not contact with said substrate holding piece of said substrate rack.

14. A cleaning apparatus of an electronic component comprising: means for supplying cleaning water to an object to be cleaned, a sponge member for contacting with said object to be cleaned to clean a surface thereof, means for moving said object to be cleaned and said sponge member relative to each other, and means for adjusting the resistivity value of said cleaning water to  $10M\Omega$  or less.

15. A cleaning apparatus of an electronic component according to claim 14, further comprising a soaking portion for soaking said object to be cleaned before being cleaned into said cleaning water having the resistivity value of  $10M\Omega$  or less.

16. A cleaning apparatus of an electronic component according to claim 14, further comprising means for supplying carbon dioxide gas for adjusting the resistivity value of said cleaning water to  $5M\Omega$  or less.

17. A cleaning apparatus of an electronic component according to claim 15, further comprising means for supplying carbon dioxide gas for adjusting the resistivity value of said cleaning water to  $5M\Omega$  or less.

